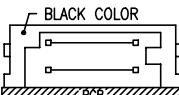
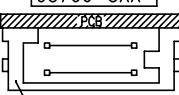
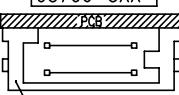


PRODUCT NO. *95706-XXX	STAND OFF DIM "M"(mm)	SOLDER TAIL	DIM "P" (mm)	SHEET NO.	Mounting Style TO PCB
000	0	R/A	2.8	NO.2	TOP MOUNT 95706-0XX BLACK COLOR 
000LF	0	R/A	2.8		
001	0	SMT STAGGERED	—/—		
002	0	SMT IN LINE	—/—		
010	4	R/A	2.8	NO.3	
020	5	R/A	2.8		
040	2	R/A	2.5		
010LF	4	R/A	2.8		
020LF	5	R/A	2.8	NO.4	BOTTOM MOUNT 95706-5XX 
040LF	2	R/A	2.5		
500	0	R/A	2.8		
500LF	0	R/A	2.8		
501	0	SMT STAGGERED	—/—	NO.5	NATURAL(WHITE) COLOR 
502	0	SMT IN LINE	—/—		
510	4	R/A	2.8		
520	5	R/A	2.8		
540	2	R/A	2.5		
510LF	4	R/A	2.8		
520LF	5	R/A	2.8		
540LF	2	R/A	2.5		

*95706-X X X X
 T T T T
 LEAD FREE LF
 SOLDER TAIL
 STAND OFF
 MOUNTING STYLE

0 : R/A (FOR LOWER & SINGLE)
 1 : SMT STAGGERED (FOR LOWER ONLY)
 2 : SMT IN LINE (FOR LOWER ONLY)
 5 : R/A (FOR UPPER ONLY)

0 : 0mm
 1 : 4mm
 2 : 5mm
 4 : 2mm

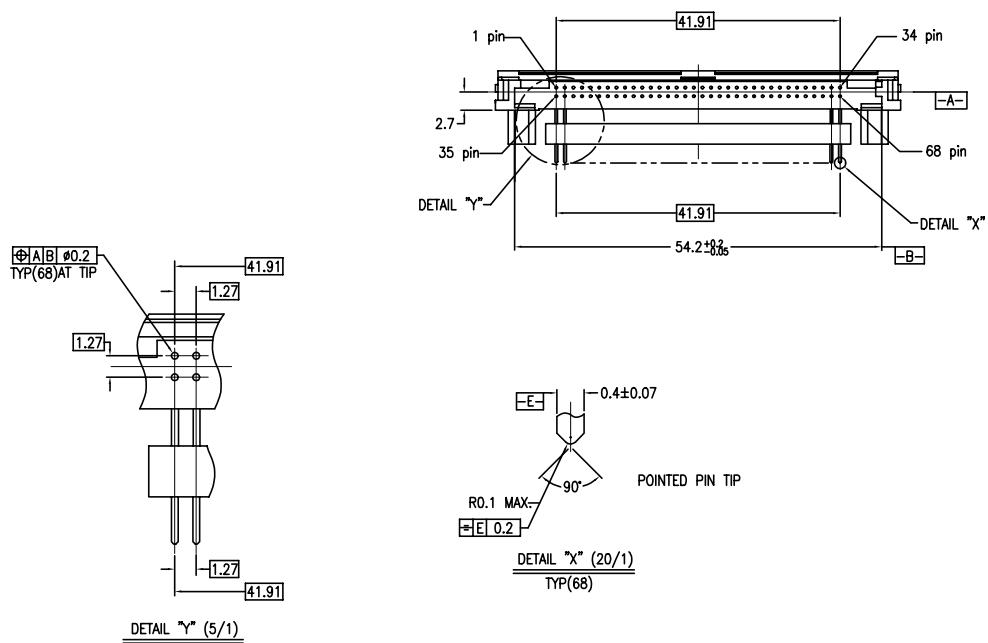
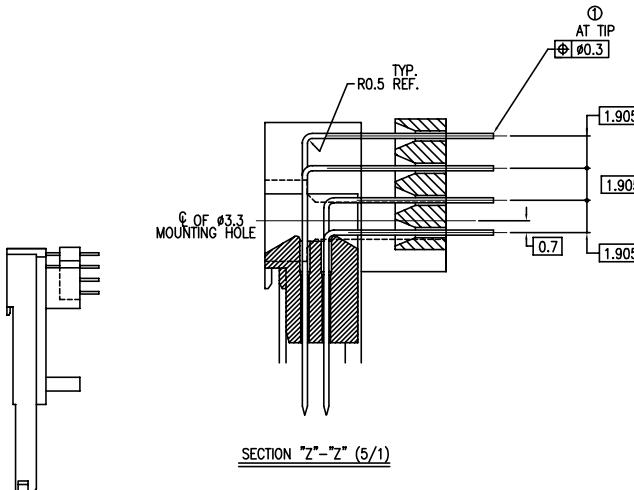
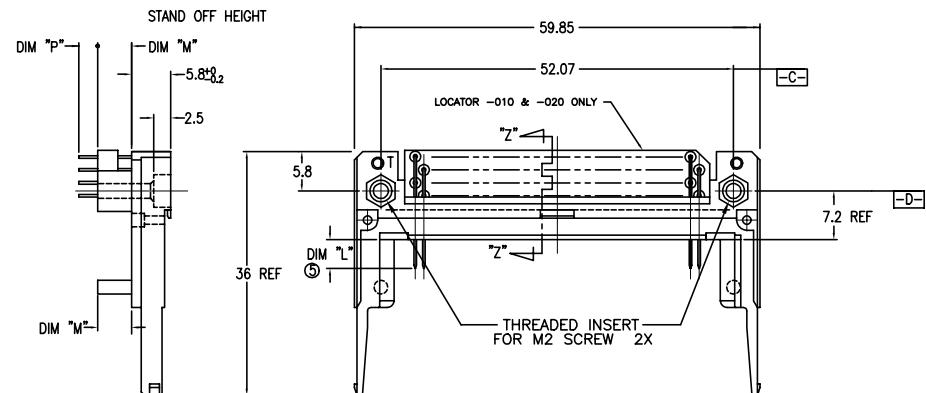
0 : TOP MOUNTING
 5 : BOTTOM MOUNTING

mat'l. code			surface	tolerance	projection	product family
ltr	ecn	nodr	ISD1101	ISD406	spec	MCS
B	V00619	RGD	3/30/00	0.0±0.3	MM	68 POS. EJECTOR HEADER ASSY.
C	N05-0048	WB	05/29/03	0.0XX±0.13		FOR LOW VOLTAGE
D	EX-N-01145	ZK	04/02/12	0.0XX±0.051	scale 1:1	
				dir S.DUESTERHOEF	7/20/95	
				engr D.BRANN	7/20/95	
				chr D.BRANN	7/20/95	
				oppd D.BRANN	7/20/95	
sheet	revision	D	D	D		
index	sheet	1	2	3	4	5

FCI

dwg no sheet 1 of 5 size
95706 A4
type Product Customer Drawing

PRODUCT NO.
95706-010/010LF
95706-020/020LF
95706-040/040LF



NOTES

① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
 2 SEE TA-946 FOR PCB LAYOUT.

③ MATERIAL
 HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
 PIN : PHOSPHOR BRONZE.

④ FINISH
 PIN
 UNDER PLATING : $0.5\mu\text{m}$ MIN. Ni.
 CONTACT AREA : $0.076\mu\text{m}$ MIN. GOLD

SOLDER AREA(TIN LEAD OPTION): $2.5\mu\text{m}$ MIN. Sn-Pb
 SOLDER AREA(LEAD FREE OPTION): $2.5\mu\text{m}$ MIN. PURE TIN

⑤ SEQUENCE PIN ASSIGNMENT

	DIM "L"		
4.25±0.1	3.5±0.1	5.0±0.1	
PIN No.	36.67	37.73	35.51.68
OTHERS			

6 GENERAL TOLERANCE : ± 0.3

7 IF LEAD FREE P/N. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE
 SOLDER TAIL : SMT-IL, SMT-STG CAN RESIST 40 SECONDS IN A CONVECTION,
 INFRA-RED OR VAPOR PHASE REFLOW OVEN.

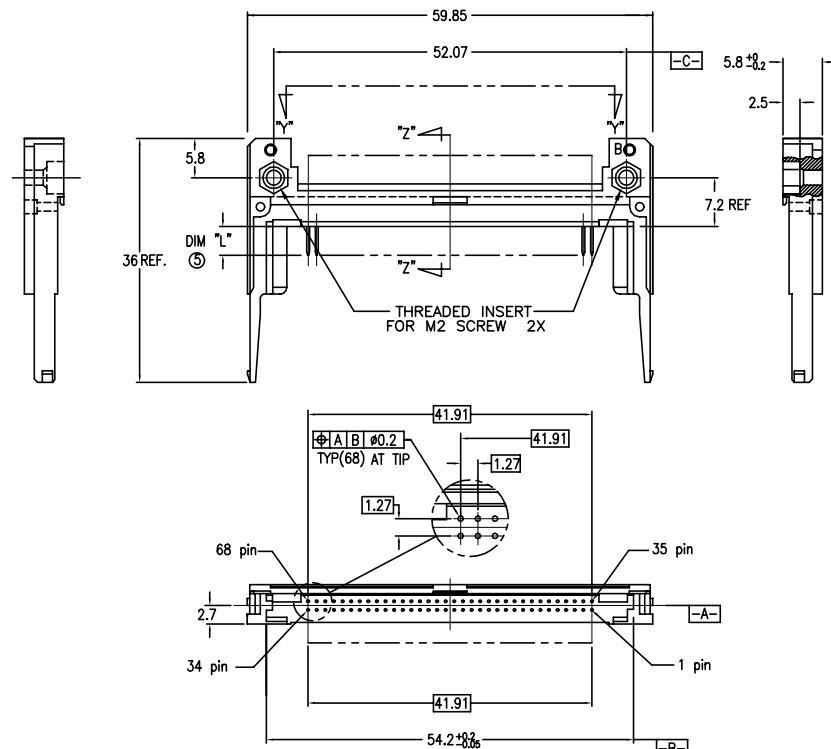
SOLDER TAIL : R/A CAN RESIST 10 SECONDS IN A WAVE SOLDER APPLICATION
 WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.

8 IF LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION

9 PRODUCT SPEC:110-263

mat'l. code			surface	tolerance	projection	product family					
			IS-1302	✓ IS-1101 IS-0406		MCS					
ltr	ecn	ndr	date		tolerances unless otherwise specified		title				
D					angle	0.0±0.3	MM				
					line	0.0XX±0.13					
					0°±2'	0.0XXX±0.051	scale 1:1				
					dr	S.DUESTERHOEF	7/20/95		dwg no	sheet 3 of 5	size
					engr	D.BRANN	7/20/95		95706		A4
					chr	D.BRANN	7/20/95		type Product Customer Drawing		
					appd	D.BRANN	7/20/95				
sheet	revision										
index	sheet										

PRODUCT NO.
95706-500/500LF
95706-501
95706-502



NOTES

① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF
2 SEE TA-946 FOR PCB LAYOUT

③ MATERIAL

HOUSING : HIGH TEMPERATURE THERMO
 PIN : PHOSPHOR BRONZE
 NISH
 PIN
 UNDER PLATING : $0.5\mu\text{m}$ MIN. Ni
 CONTACT AREA : $0.076\mu\text{m}^2$ MIN. GOLD

SOLDER AREA(TIN LEAD OPTION): 2.5 μ m MIN. Sn-Pb
SOLDER AREA(LEAD FREE OPTION): 2.5 μ m MIN. PURE TIN

⑤ SEQUENCE PIN ASSIGNMENT

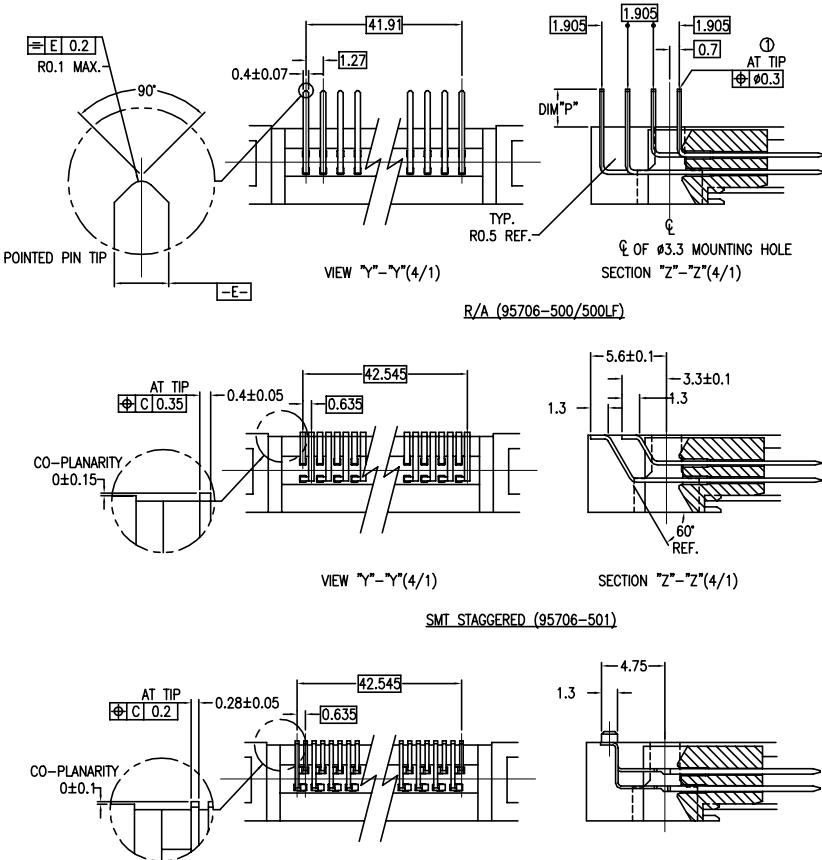
PIN No.	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36.67	1,17.34 35.51.68	

6 GENERAL TOLERANCE : ± 0.3

7 IF LEAD FREE P/N THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE
SOLDER TAIL : SMT-IL, SMT-STG CAN RESIST 40 SECONDS IN A CONVECTION,
INFRA-RED OR VAPOR PHASE REFLOW OVEN.
SOLDER TAIL : R/A CAN RESIST 10 SECONDS IN A WAVE SOLDER APPLICATION
WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.

8 IF LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION

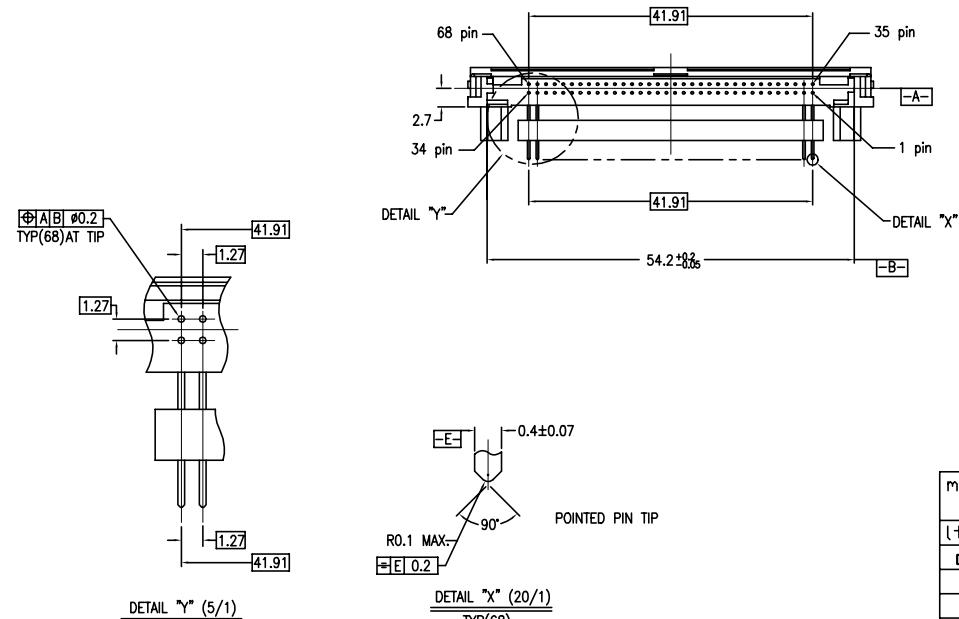
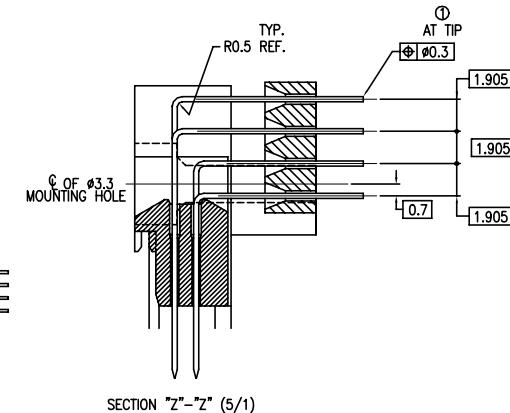
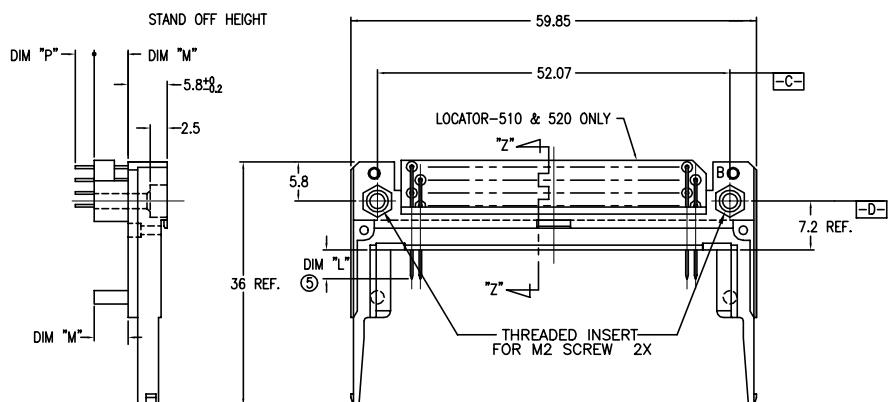
9 PRODUCT SPEC:110-263



ANSWER (ANSWER-SEE)

mat'l. code			surface ISD1302	tolerance ISO1101 ISO406	projection wise specified	product family MCS			
ltr	ecn	ndr	date	tolerances unless otherwise specified					
D				angle 0° \pm 0.3	MM	68 POS. EJECTOR HEADER ASSY. FOR LOW VOLTAGE			
				0.25 0.25 0° \pm 2°	0.05 0.05 0.005 \pm 0.051				
				scale 1:1					
			dr	S.DUESTERHOEF	7/20/95	dwg no	sheet 4 of 5	size	
			engr	D.BRANN	7/20/95				
			chr	D.BRANN	7/20/95				
			appd	D.BRANN	7/20/95	95706 A4			
sheet	revision					type	Product	Customer	Drawing
index	sheet								

PRODUCT NO.
95706-510/510LF
95706-520/520LF
95706-540/540LF



NOTES

① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF

2 SEE TA-946 FOR PCB LAYOUT

③ MATERIAL

 HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 NATURAL

 PIN : PHOSPHOR BRONZE

④ FINISH

 PIN
 UNDER PLATING : 0.5 μ m MIN. Ni
 CONTACT AREA : 0.076 μ m MIN. GOLD

SOLDER AREA(TIN LEAD OPTION): 2.5 μ m MIN. Sn-Pb

SOLDER AREA(LEAD FREE OPTION): 2.5 μ m MIN. PURE TIN

⑤ SEQUENCE PIN ASSIGNMENT

	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	33.51/38

6 GENERAL TOLERANCE : ±0.3

7 IF LEAD FREE P/N. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C TEMPERATURE

SOLDER TAIL : SMT-IL, SMT-STG CAN RESIST 40 SECONDS IN A CONVE INFRA-RED OR VAPOR PHASE REFLOW OVEN.

SOLDER TAIL : R/A CAN RESIST 10 SECONDS IN A WAVE SOLDER APPL WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.

8 IF LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION

9 PRODUCT SPEC:110-263

mat'l. code		surface	tolerance	projection	product family			
		ISD1302	✓ ISD1101 ISD406		MCS			
ltr	ecn	no dr	date	tolerances unless otherwise specified		title		
D				angle $0^\circ \pm 0.3$	MM	68 POS. EJECTOR HEADER ASSY.		
				line $0.0X \pm 0.13$		FOR LOW VOLTAGE		
				arc $0^\circ \pm 2^\circ$	scale 1:1			
				dr S.DUESTERHOEF	7/20/95	dwg no	sheet 5 of 5	size
				engr D.BRANN	7/20/95		95706	A4
				chr D.BRANN	7/20/95			
				appd D.BRANN	7/20/95			
sheet	revision							
index	sheet							

Mouser Electronics

Authorized Distributor

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FCI:

95706-020LF